



MOTEVM-HSFN

- Supplemental cooling fan and heatsink for MOTEVM-OBJ Object Board
- 12-V Operation



MOTOEM-HSFN

The MOTOEM-HSFN is intended to be used in conjunction with the MOTEVM-OBJ Object Board. It's function is to assist with heat dissipation from the "hot" side of the TEC to allow cooler object temperatures to be obtained.

This assembly consists of a 40mm x 40mm heatsink with an attached fan. The fan operates from 12V dc, consumes ~80mA, provides ~7cfm airflow and has a noise rating of 27dBA.

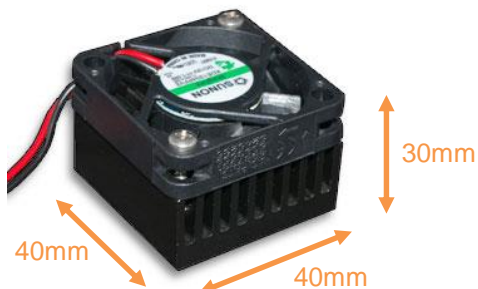


MOTOEM-HSFN attached to Object Board

Note: The assembly may be either clamped to the TEC or attached using thermal epoxy.



Dimensions (approximate)



Ordering Information

Part Number	Description
MOTOEM-HSFN	Heatsink and Fan

For further information please refer to the MOT705-OEM User's Guide.

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